

Specifications

Insulation Resistance:	1,000M Ω min. at 500V DC
Dielectric Withstanding Voltage:	700V AC for 1 minute
Contact Resistance:	30m Ω max. at 10mA/20mV max.
Operating Temperature Range:	-55°C to +170°C
Mating Cycles:	10,000 insertions min.
Pin Count:	160 contact pins

Materials and Finish

Housing: Polyetherimide (PEI), glass-filled
 Contacts: Beryllium Copper (BeCu)
 Plating: Gold over Nickel

Features

- Card thickness 1.57mm

Part Number (Details)

IC-553 - 1 - MF

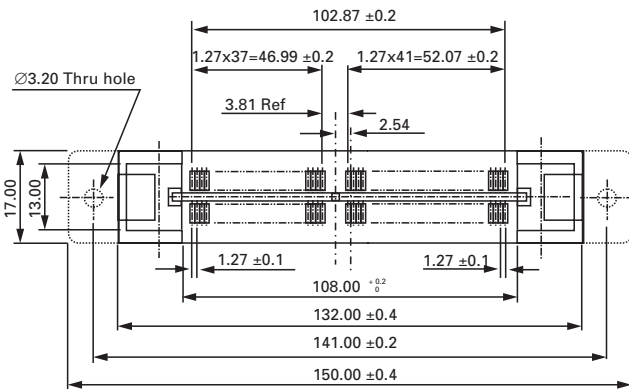
Series No.

Design No.

MF = Flanged
 Unmarked = Not Flanged

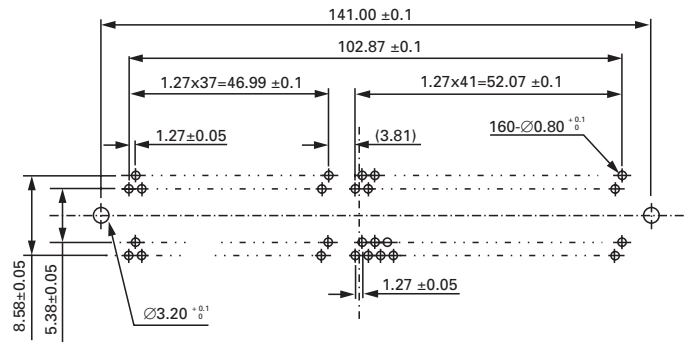


Outline Socket Dimensions



Recommended PC Board Layout

Top View from Socket



Matching Module Dimensions

